

20V P-Channel Enhancement Mode MOSFET

Description

The NP3417BEMR uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications.

General Features

- ◆ $V_{DS} = -20V$, $I_D = -3A$
 $R_{DS(ON)}(\text{Typ.}) = 51.8\text{m}\Omega$ @ $V_{GS} = -4.5V$
 $R_{DS(ON)}(\text{Typ.}) = 72.7\text{m}\Omega$ @ $V_{GS} = -2.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ ESD Rating: 2500V HBM

Application

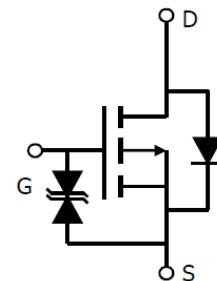
- ◆ PWM applications
- ◆ Load switch

Package

- ◆ SOT-23-3L

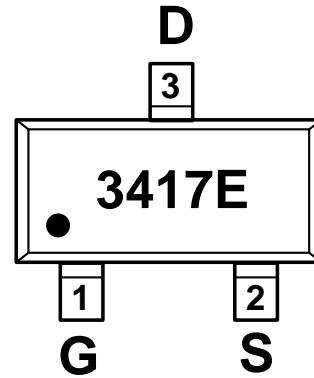


Schematic diagram



Marking and pin assignment

SOT-23-3L
(TOP VIEW)



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP3417BEMR-G	-55°C to +150°C	SOT-23-3L	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-20	V
Gate-source voltage	V_{GS}	± 8	V
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	A
	$T_C = 70^\circ\text{C}$		
Continuous Source-Drain Diode Current	I_S	-2.1	
Pulsed Drain Current ($t = 300 \mu\text{s}$)	I_{DM}	-12	
Maximum power dissipation	$T_C = 25^\circ\text{C}$	P_D	W
	$T_C = 70^\circ\text{C}$		
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-20	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V	-	-	-1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±8V	-	-	±10	μA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.45	-0.7	-0.95	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-3A	-	51.8	60	mΩ
		V _{GS} =-2.5V, I _D =-3A	-	72.7	83	
Forward transconductance	g _{fs}	V _{GS} =-5V, I _D =-3A	8	-	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =-10V, V _{GS} =0V f=1.0MHz	-	526	-	pF
Output capacitance	C _{OSS}		-	79.1	-	
Reverse transfer capacitance	C _{RSS}		-	58.6	-	
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DD} =-10V I _D =-2.8A V _{GEN} =-4.5V R _L =5Ω R _{GEN} =3Ω	-	8	-	ns
Rise time	tr		-	4	-	
Turn-off delay time	t _{D(OFF)}		-	13.5	-	
Fall time	tf		-	4	-	
Total gate charge	Q _g	V _{DS} =-10V, I _D =-3A V _{GS} =-4.5V	-	11	-	nC
Gate-source charge	Q _{gs}		-	1.3	-	
Gate-drain charge	Q _{gd}		-	1.4	-	
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode forward voltage	V _{SD}	V _{GS} =0V, I _s =-1.25A	-	-0.81	-1.2	V

Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R _{θJA}	100	130	°C/W
Maximum Junction-to-Foot (Drain)	R _{θJF}	60	75	

Typical Performance Characteristics

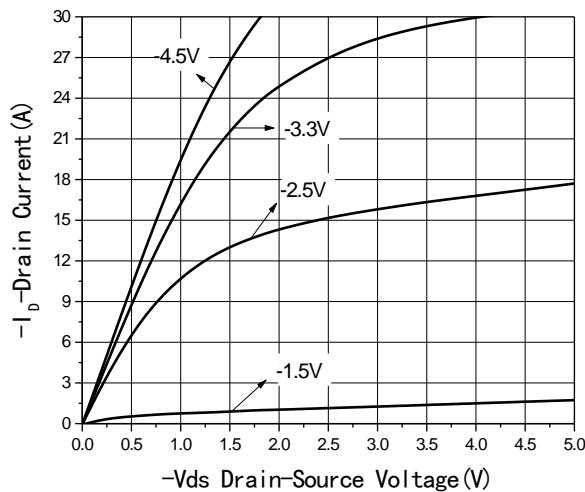


Fig1 Output Characteristics

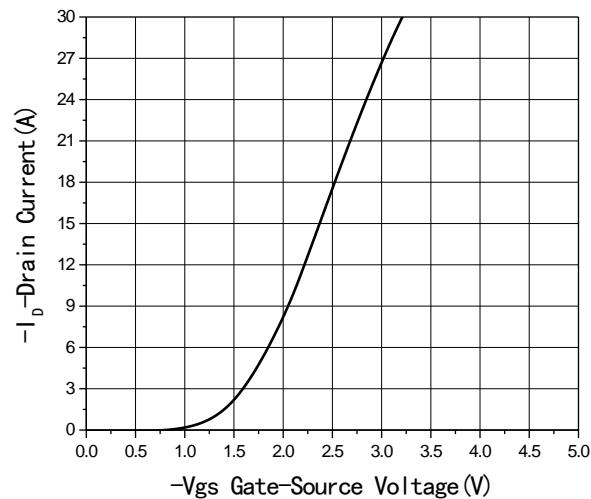


Fig2 Transfer Characteristics

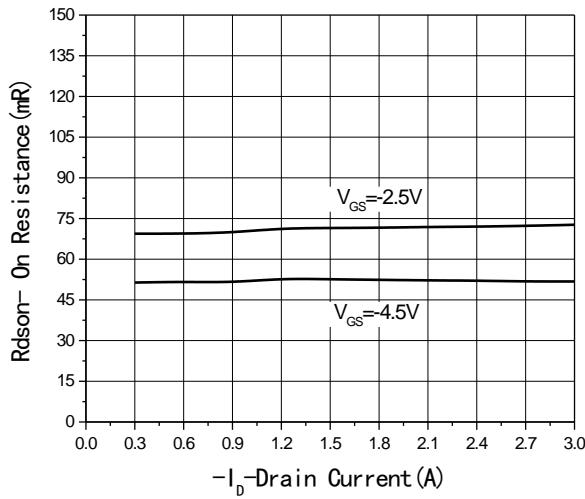


Fig3 Rdson-Drain current

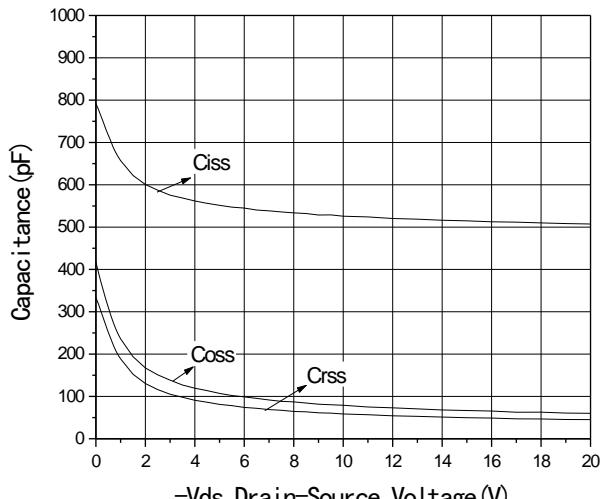


Fig4 Capacitance vs Vds

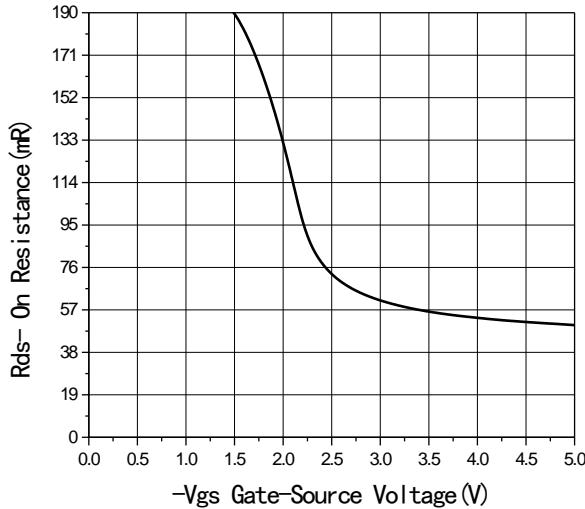


Fig5 Rdson-Gate Drain voltage

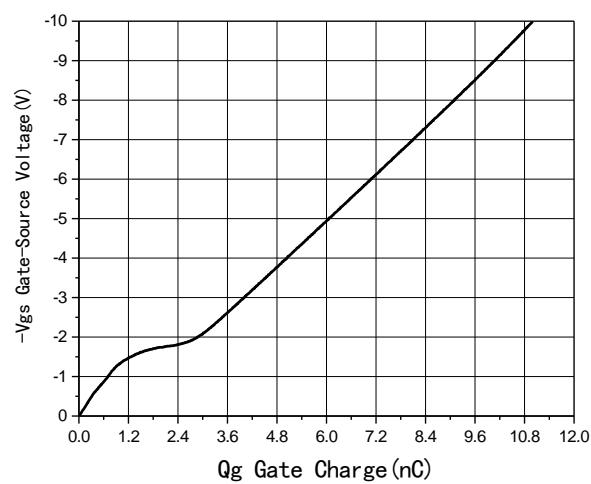
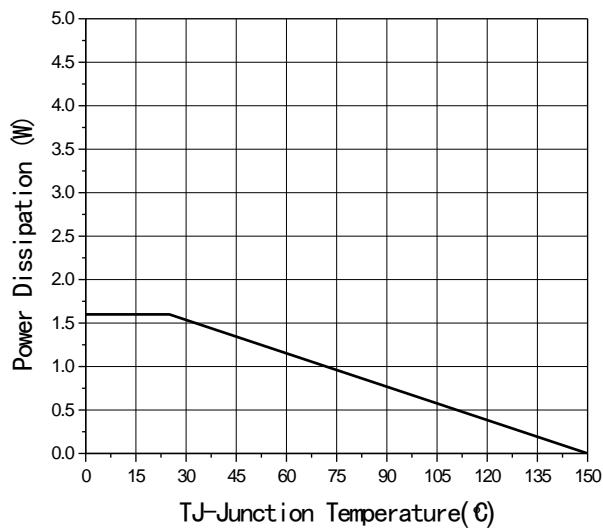
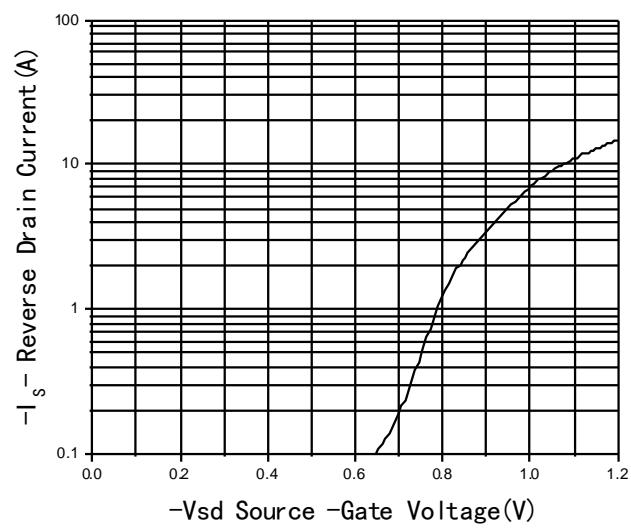
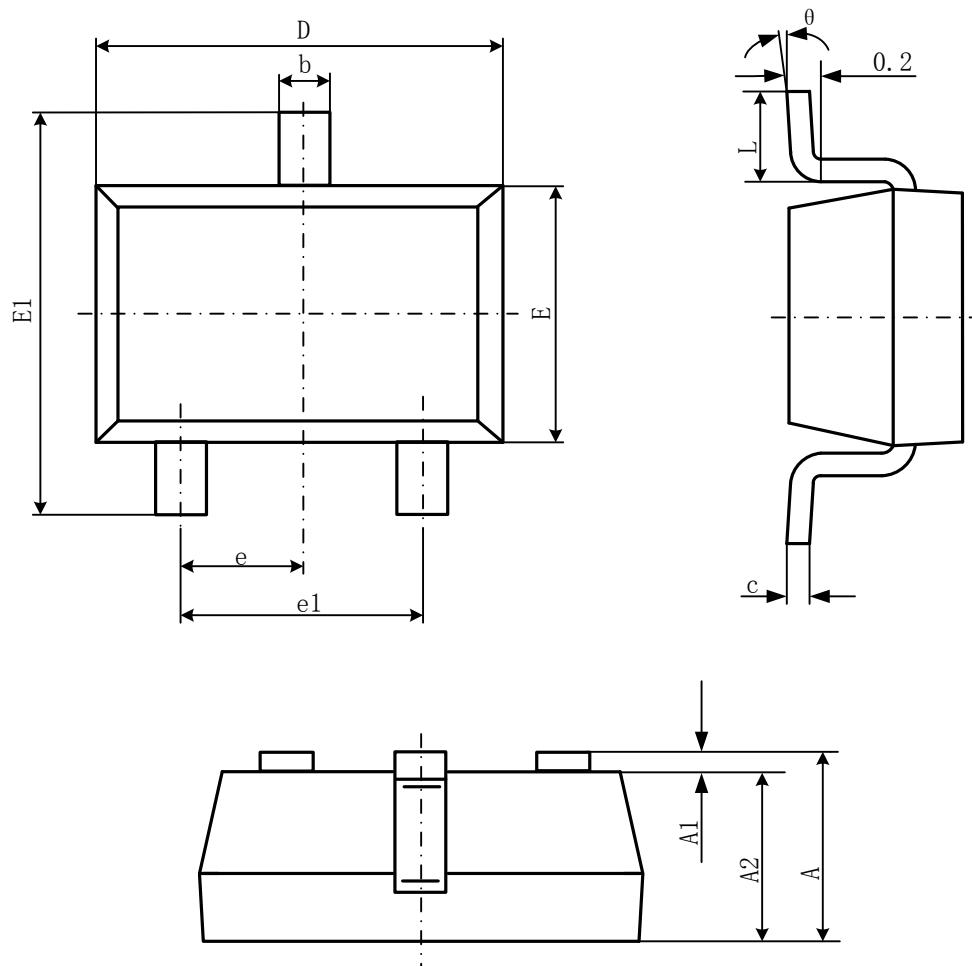


Fig6 Gate Charge


Fig7 Power De-rating

Fig8 Source-Drain Diode Forward

Package Information

- SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°